



IEC/PAS 62588

Edition 1.0 2008-09

PUBLICLY AVAILABLE SPECIFICATION

Marking and labeling of components, PCBs and PCBAs to identify lead(Pb),
Pb-free and other attributes

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ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES®

IPC/JEDEC J-STD-609



Marking and Labeling of Components, PCBs and PCBAs to Identify Lead(Pb), Pb-Free and Other Attributes

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A joint standard developed by the Marking, Symbols and Labels
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Users of this publication are encouraged to participate in the
development of future revisions.

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IPC/JEDEC FOREWORD

Directive 2002/95/EC of the European Parliament and of the Council on the restriction of the use of certain hazardous substances in electrical and electronic equipment, commonly referred to as the “RoHS Directive”¹, and other legislation are driving the electronics industry towards the use of lead free (Pb-free) solders and components with Pb-free 2nd level interconnect terminal finishes and materials.

There are different Pb-free solders being used for the various soldering operations in electronics. Each of these solders may require different processing temperatures for assembly, rework, and repair. Some means of communicating the identity of the Pb-free or Pb-containing solder must be provided so that those performing assembly, rework and repair are aware of the temperature capabilities and limitations of these solders, and are able to distinguish between Pb-free and Pb-containing solders.

Marking of components and/or labeling their shipping containers are needed to identify and distinguish Pb-containing and Pb-free 2nd level interconnect terminal finishes and materials. Labeling electronic assemblies using Pb-free solder materials will facilitate end-of-life recycling of electronic equipment. This standard sets forth minimum requirements and includes options for the provision of additional information.

This paradigm shift to Pb-free electronics has created a need for identification of traditional Pb-containing coatings, finishes and solders. This standard can be utilized to identify the presence of lead (Pb) for those markets as described in Clauses 5 (Marking/Labeling Categories) and 8 (Marking and/or Labeling of Pb-Containing Components, PCBs, and PCB Assemblies). This standard supersedes JESD97 and IPC-1066.

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1. The RoHS Directive itself is not a law; rather, it is a direction to the European Union Member States to implement their own laws embodying the requirements of the Directive. These laws were required to be in effect as of July 1, 2006.

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